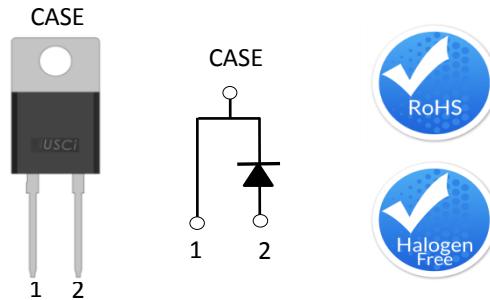


Description

United Silicon Carbide, Inc. offers the xR series of high performance SiC Schottky diodes. With zero reverse recovery charge and 175°C maximum junction temperature, USCI's diodes are ideally suited for high frequency and high efficiency power systems with minimum cooling requirements.



Part Number	Package	Marking
UJD06506TS	TO-220-2L	UJD06506TS

Features

- ◆ Positive temperature coefficient for safe operation and ease of paralleling
- ◆ 175°C maximum operating junction temperature
- ◆ Extremely fast switching not dependent on temperature
- ◆ Essentially no reverse or forward recovery
- ◆ Enhanced surge capability
- ◆ RoHS compliant
- ◆ Power converters
- ◆ Industrial motor drives
- ◆ Switching-mode power supplies
- ◆ Power factor correction modules

Typical Applications

Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units
DC blocking voltage	V_R		650	V
Repetitive peak reverse voltage, $T_j=25^\circ\text{C}$	V_{RRM}		650	V
Surge peak reverse voltage	V_{RSM}		650	V
Maximum DC forward current	I_F	$T_C = 153^\circ\text{C}$	6	A
Non-repetitive forward surge current sine halfwave	I_{FSM}	$T_C = 25^\circ\text{C}, t_p = 10\text{ms}$	45	A
		$T_C = 110^\circ\text{C}, t_p = 10\text{ms}$	36	
Repetitive forward surge current sine halfwave, $D=0.1$	I_{FRM}	$T_C = 25^\circ\text{C}, t_p = 10\text{ms}$	30.6	A
		$T_C = 110^\circ\text{C}, t_p = 10\text{ms}$	18	
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25^\circ\text{C}, t_p = 10\mu\text{s}$	310	A
		$T_C = 110^\circ\text{C}, t_p = 10\mu\text{s}$	279	
Non-repetitive avalanche energy	E_{AS}	$T_j = 25^\circ\text{C}, L = 5\text{mH}, I_{pk}=4.25\text{A}, V_{DD}=100\text{V}$	50	mJ
Power dissipation	P_{Tot}	$T_C = 25^\circ\text{C}$	93	W
		$T_C = 153^\circ\text{C}$	13.7	
Maximum junction temperature	$T_{j,max}$		175	°C
Operating and storage temperature	T_j, T_{STG}		-55 to 175	°C
Soldering temperatures, wavesoldering only allowed at leads	T_{sold}	1.6mm from case for 10s	260	°C

Electrical Characteristics

$T_J = +25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Forward voltage	V_F	$I_F = 6\text{A}, T_J = 25^\circ\text{C}$	-	1.5	1.7	V
		$I_F = 6\text{A}, T_J = 150^\circ\text{C}$	-	1.8	2.1	
		$I_F = 6\text{A}, T_J = 175^\circ\text{C}$	-	2	2.25	
Reverse current	I_R	$V_R = 650\text{V}, T_J = 25^\circ\text{C}$	-	15	200	μA
		$V_R = 650\text{V}, T_J = 175^\circ\text{C}$	-	30	640	
Total capacitive charge ⁽¹⁾	Q_C	$V_R = 400\text{V}$		12.7		nC
Total capacitance	C	$V_R = 1\text{V}, f = 1\text{MHz}$		179		pF
		$V_R = 300\text{V}, f = 1\text{MHz}$		21		
		$V_R = 600\text{V}, f = 1\text{MHz}$		18		
Capacitance stored energy	E_C	$V_R = 400\text{V}$		1.9		μJ

(1) See Figure 8, Q_c is independent on T_j , di_F/dt , and I_F as shown in the application note USCI_AN0011.

Thermal characteristics

Parameter	symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Thermal resistance	R_{0JC}			1.2	1.6	$^\circ\text{C}/\text{W}$

Typical Performance

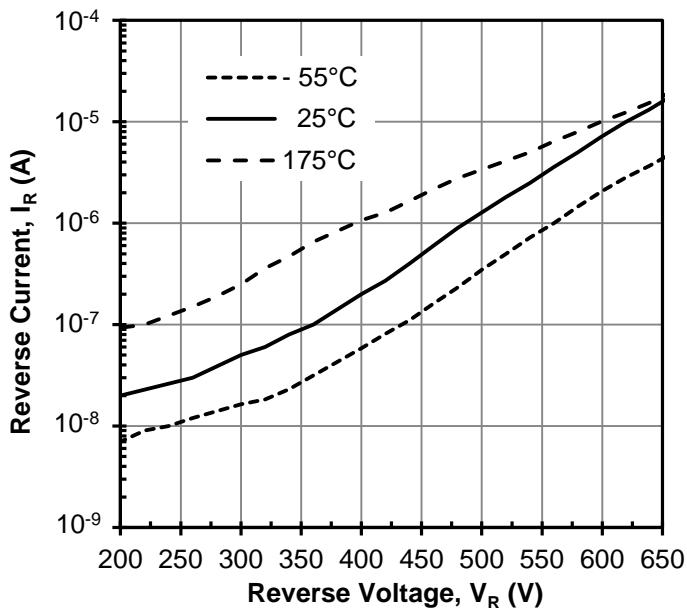


Figure 1 Typical reverse characteristics

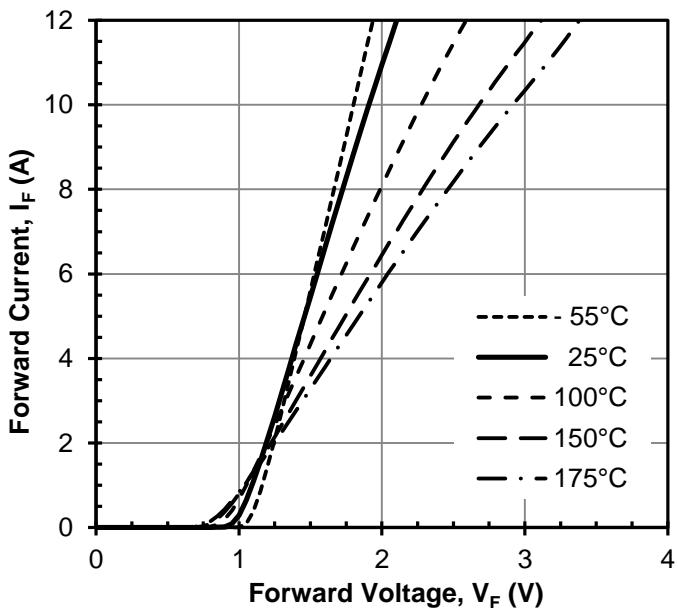
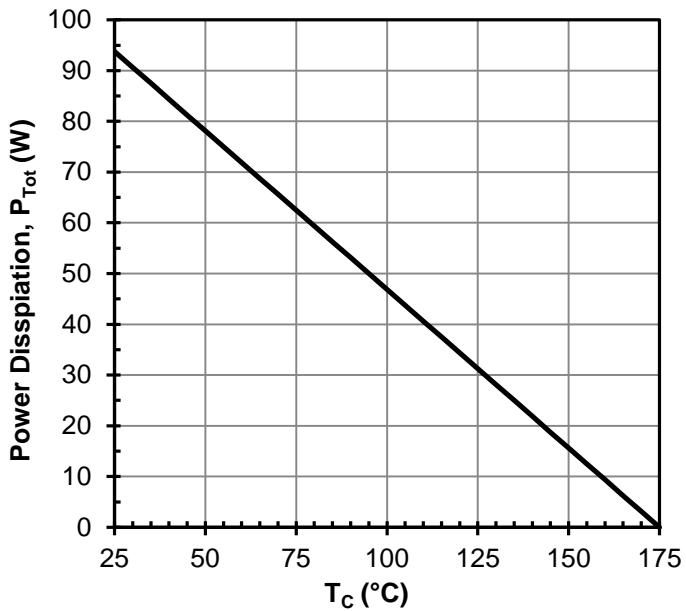
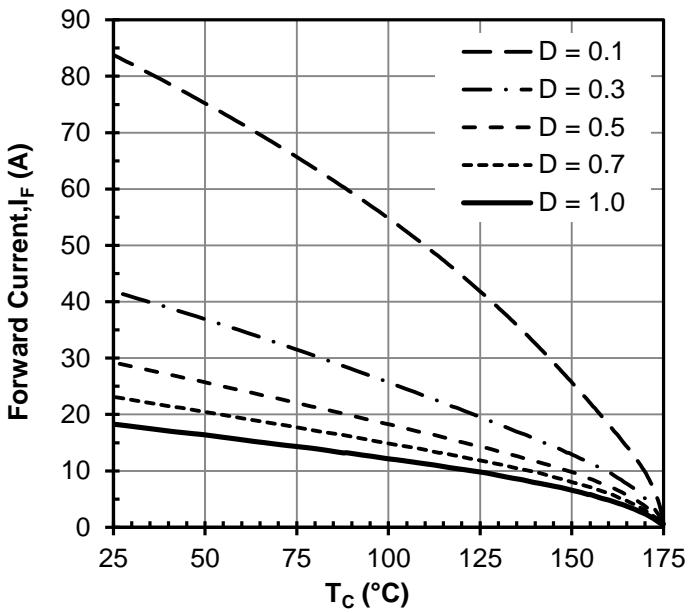
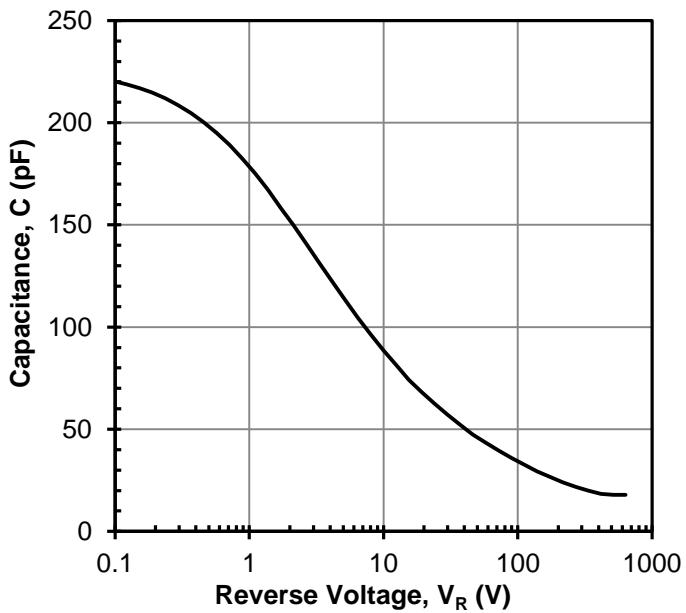
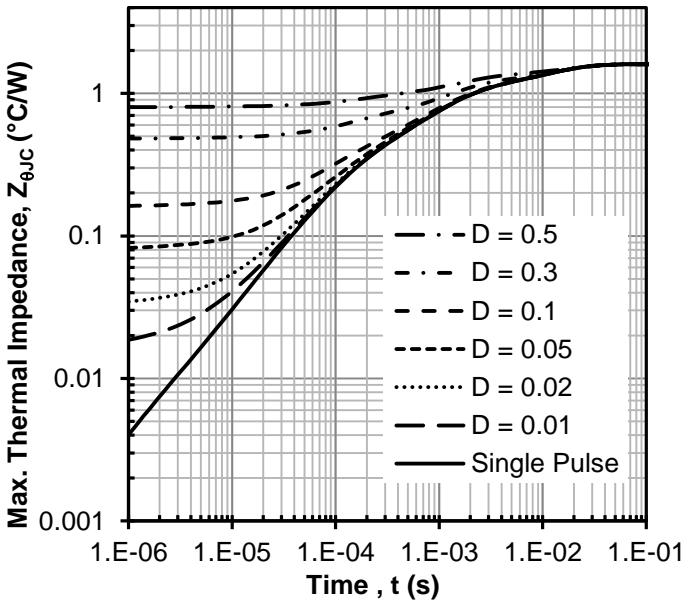


Figure 2 Typical forward characteristics

**Figure 3 Power dissipation****Figure 4 Diode forward current****Figure 5 Capacitance vs. reverse voltage****Figure 6 Maximum transient thermal impedance**

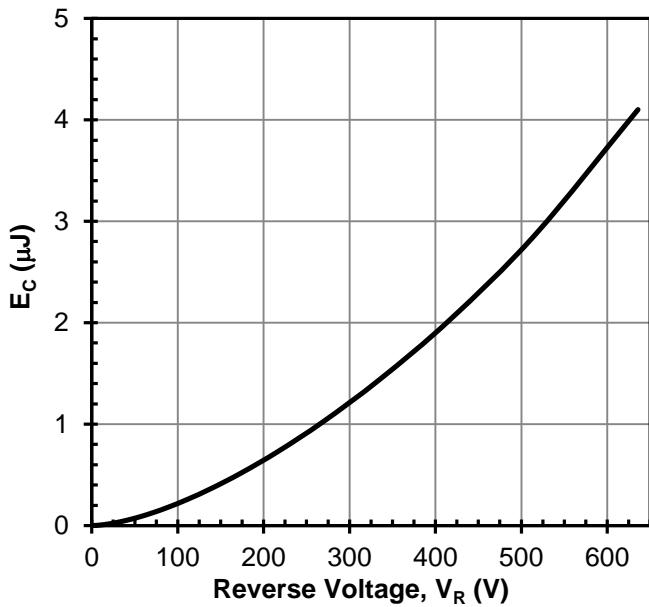


Figure 7 Typical capacitance stored energy vs. reverse voltage

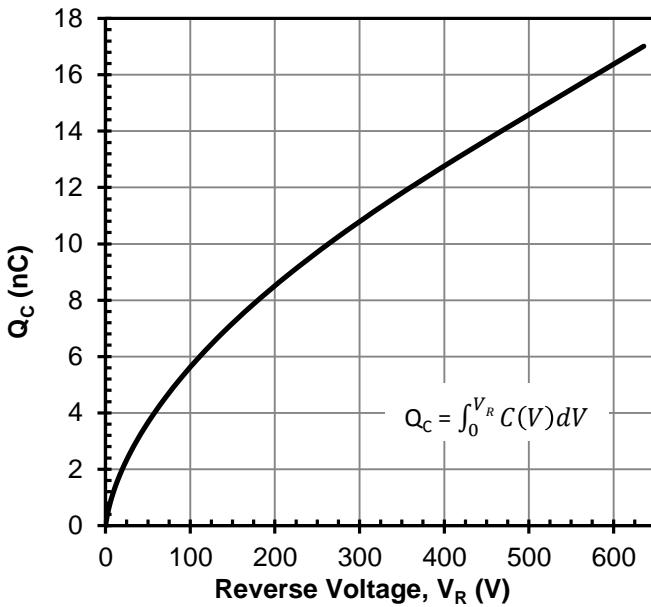


Figure 8 Typical capacitive charge vs. reverse voltage

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